imall

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8A, 400V - 1000V Surface Mount Glass Passivated Rectifier

FEATURES

- Low forward voltage drop
- Ideal for automated placement
- High surge current capability
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

- Switching mode power supply (SMPS)
- Adapters
- Lighting application
- Converter

MECHANICAL DATA

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Part no. with suffix "H" means AEC-Q101 qualified
- Packing code with suffix "G" means green compound (halogen-free)
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: As marked
- Weight: 0.27 g (approximately)

KEY PARAMETERS						
PARAMETER	PARAMETER VALUE UNIT					
I _{F(AV)}	8	А				
V _{RRM}	400 - 1000	V				
I _{FSM}	200	А				
T _{J MAX}	150	°C				
Package	DO-214AB (SMC)					
Configuration	Single die					





DO-214AB (SMC)

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)							
PARAMETER		SYMBOL	S8GC	S8JC	S8KC	S8MC	UNIT
Marking code on the device			S8GC	S8JC	S8KC	S8MC	
Repetitive peak reverse voltage		V_{RRM}	400	600	800	1000	V
Reverse voltage, total rms value		$V_{R(RMS)}$	280	420	560	700	V
Maximum DC blocking voltage		V _{DC}	400	600	800	1000	V
Forward current		I _{F(AV)}	8			А	
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load per diode $T_J = 25^{\circ}C$ T _J = 125°C		I	200 170			А	
		FSM				А	
Surge peak forward current, 1.0 ms T _{.1} =25°C		I		60	00		А
single half sine-wave superimposed on $T_J = 125^{\circ}C$		FSM	338		А		
Junction temperature		TJ	- 55 to +150		°C		
Storage temperature		T _{STG}	- 55 to +150			°C	



THERMAL PERFORMANCE						
PARAMETER	SYMBOL	LIMIT	UNIT			
Junction-to-lead thermal resistance per diode	R _{eJL}	12.5	°C/W			
Junction-to-ambient thermal resistance per diode	R _{eJA}	44.0	°C/W			

ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
Forward voltage per diode (1)	$I_F = 8A, T_J = 25^{\circ}C$	V _F	-	0.985	V	
$\mathbf{P}_{\mathbf{r}}$	$T_J = 25^{\circ}C$		-	10	μA	
Reverse current @ rated V_R per diode $^{(2)}$	T _J = 125°C	IR	-	250	μA	
Junction capacitance	1 MHz, V _R =4.0V	CJ	48	-	pF	

Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

DRDERING INFORMATION						
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
	H	R7	G	SMC	850 / 7" Plastic reel	
		R6		SMC	3,000 / 13" Paper reel	
S8xC (Note 1)		M6		SMC	3,000 / 13" Plastic reel	
		V7		Matrix SMC	850 / 7" Plastic reel	
		V6		Matrix SMC	3,000 / 13" Plastic reel	

Note :

1. "x" defines voltage from 400V (S8GC) to 1000V (S8MC)

EXAMPLE						
EXAMPLE P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION	
S8GCHR7G	S8GC	Н	R7	G	AEC-Q101 qualified Green compound	



CHARACTERISTICS CURVES

(T_A = 25°C unless otherwise noted)

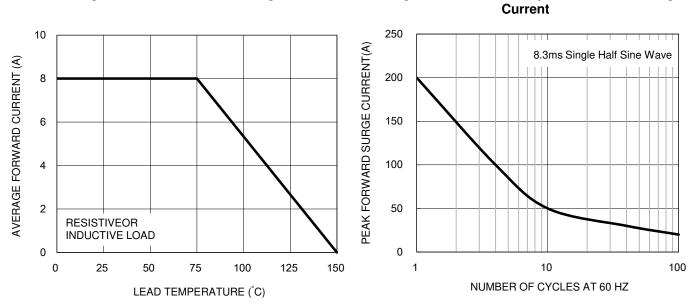
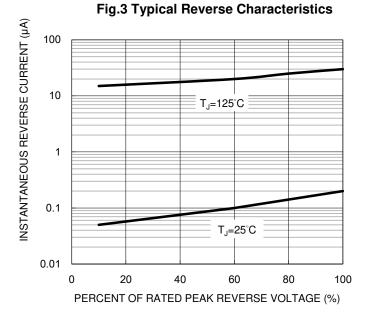
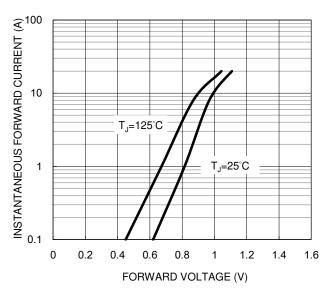


Fig.1 Forward Current Derating Curve



Fig.2 Maximum Non-repetitive Forward Surge

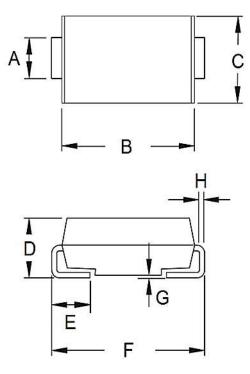






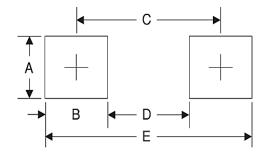
PACKAGE OUTLINE DIMENSIONS

DO-214AB (SMC)



DIM.	Unit	(mm)	Unit (inch)		
DIM.	Min.	Max.	Min.	Max.	
А	2.90	3.20	0.114	0.126	
В	6.60	7.11	0.260	0.280	
С	5.59	6.22	0.220	0.245	
D	2.00	2.62	0.079	0.103	
E	1.00	1.60	0.039	0.063	
F	7.75	8.13	0.305	0.320	
G	0.10	0.20	0.004	0.008	
Н	0.15	0.31	0.006	0.012	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
А	3.30	0.130
В	2.50	0.098
С	6.80	0.268
D	4.40	0.173
E	9.40	0.370

MARKING DIAGRAM



- P/N =Marking Code
- G =Green Compound
- YW =Date Code
- F =Factory Code



Taiwan Semiconductor

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